

Part Number:  
KH-3030175-G1

 Checker/Date  
Henry  
06/01/18'

 Inspector/Date  
Henry  
06/01/18'

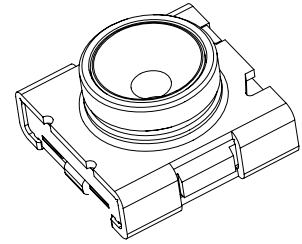
 Maker/Date  
SAM  
06/01/18'

## 1、Overview

This product is applied to RF circuits and provides a switch interface for circuit tests, And it's the first type of the "MINI RF CONNECTOR".

## 2、Technology Parameters

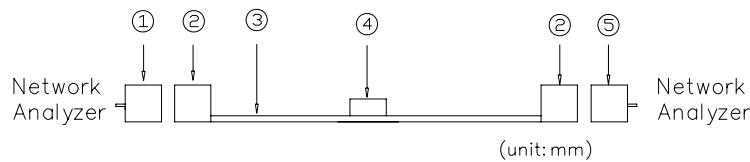
2.1 Rated Voltage	250V AC
2.2 Frequency Range	0~6GHz
2.3 Impedance	50Ω
2.4 Operating Temperature	-40°C ~ +85°C



## 3、Electrical Performance

3.1 Insulation Resistance	500MΩ
3.2 Dielectric Withstanding Voltage	300V AC
3.3 Contact Resistance	120 mΩ max
3.4 Voltage Standing Wave Ratio (VSWR)	1.2 max (DC~3GHz), 1.3 max (3~6GHz)

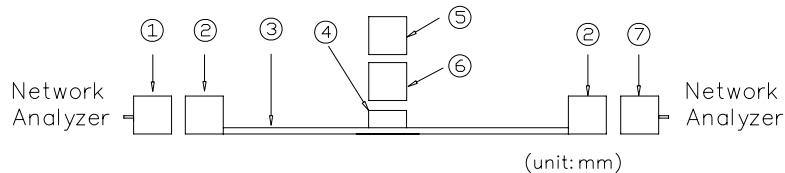
### 3.4.1 Test Methods:



- |                   |             |
|-------------------|-------------|
| ① Port 1          | ④ 818000251 |
| ② SMA Jack        | ⑤ Port 2    |
| ③ Microstrip line |             |

3.5 Isolation 20dBmin (DC~3GHz), 15dBmin (3~6GHz)

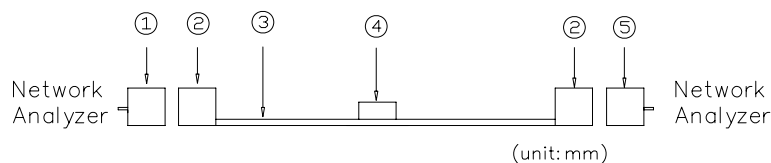
### 3.5.1 Test Methods:



- |                   |                                   |
|-------------------|-----------------------------------|
| ① Port 1          | ④ 818000251                       |
| ② SMA Jack        | ⑤ Termination                     |
| ③ Microstrip line | ⑥ Probe for automatic measurement |
|                   | ⑦ Port 2                          |

3.6 Insertion loss 0.10dBmax (DC~3GHz), 0.20dBmax (3~6GHz)

### 3.6.1 Test Methods:

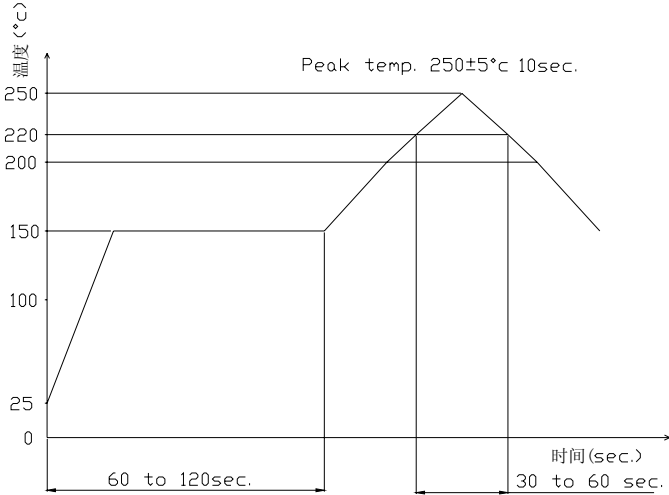


- |                   |             |
|-------------------|-------------|
| ① Port 1          | ④ 818000251 |
| ② SMA Jack        | ⑤ Port 2    |
| ③ Microstrip line |             |

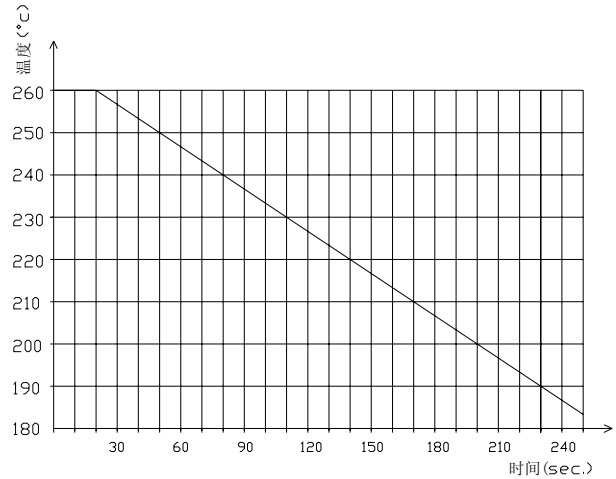


### 6、SMT Temperature Curve

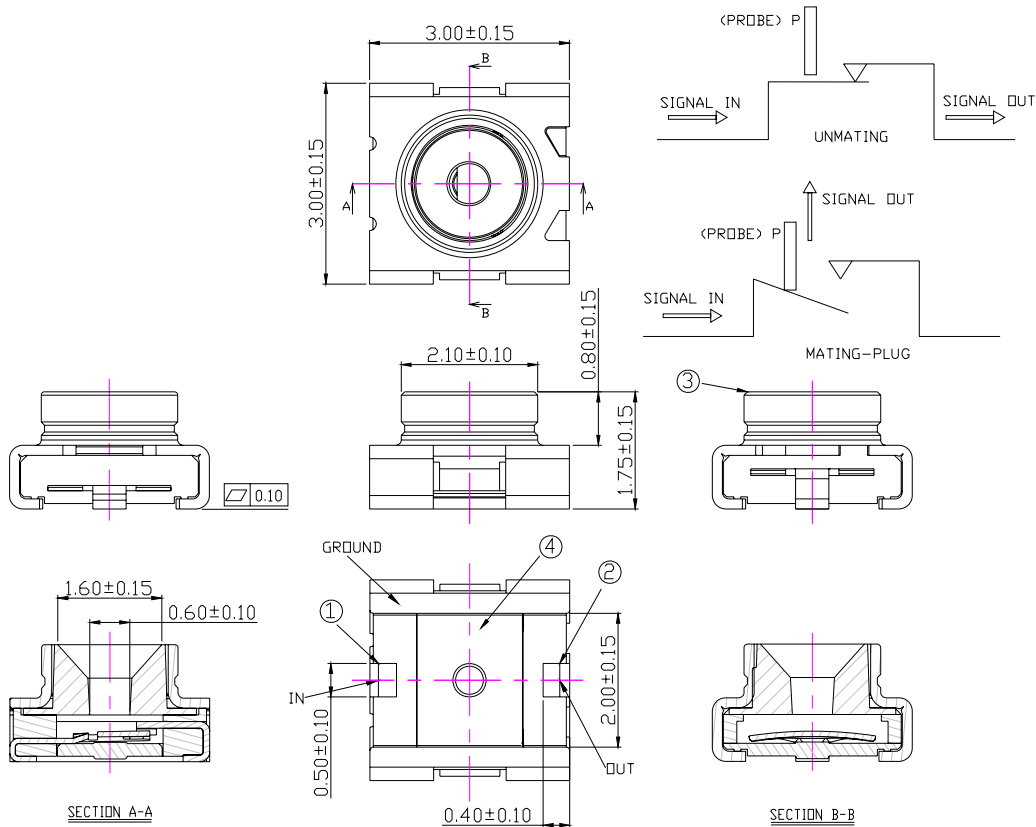
#### 6.1 Reflow Soldering Standard Conditions



#### 6.2 Allowable Temperature and Time of Reflow Soldering

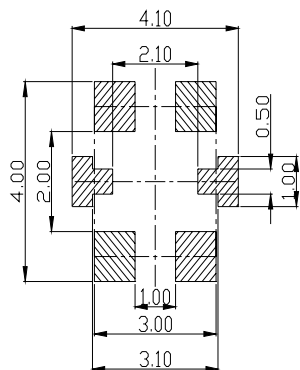


### 7、Appearance Dimension

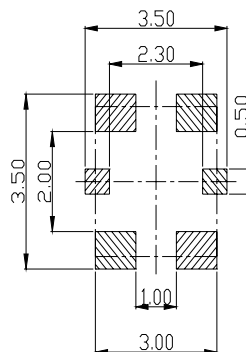


4	Case	Engineering plastic	UL 94V-0, BLACK	1
3	Output terminal	Copper Alloy	50u"Ni Overall, Contact Area Au2u", Soldering Area Gold Flash	1
2	Input terminal(R)	Copper Alloy	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
1	Input terminal(C)	Stainless Steel	50u"Ni Overall, Contact Area Au5u", Soldering Area Gold Flash	1
No.	Part Name	Material	Finish	Q'ty

### 8、Printed circuit board (PCB) pad



Recommend PCB Layout

 General Tolerance:  $\pm 0.05$ 


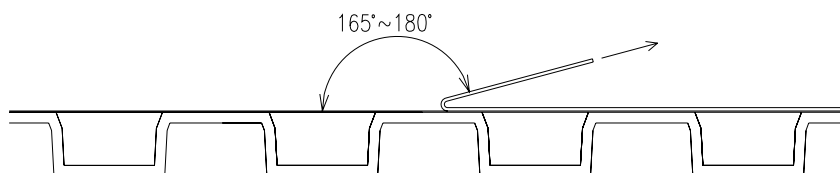
The standard solder stencil mask pattern

(Mask thickness 0.15mm)

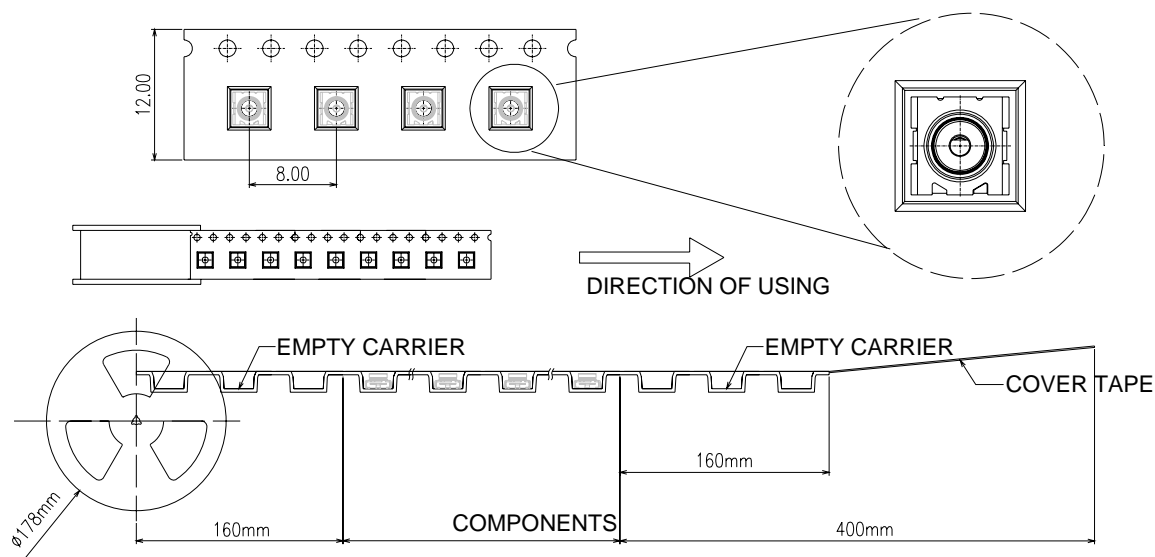
### 9、PACKING SPECIFICATIONS

#### 9.1 Peeling off Force of Cover Tape

When cover tape is peeled off as in right figure by a speed of 300mm/minute. The peeling off force should be 1.3N maximum.



#### 9.2 THE WAY OF PACKAGE : TAPE PACKING, 1000Pcs/REEL ( $\Phi 178\text{mm}$ )



### 10、Storage Conditions

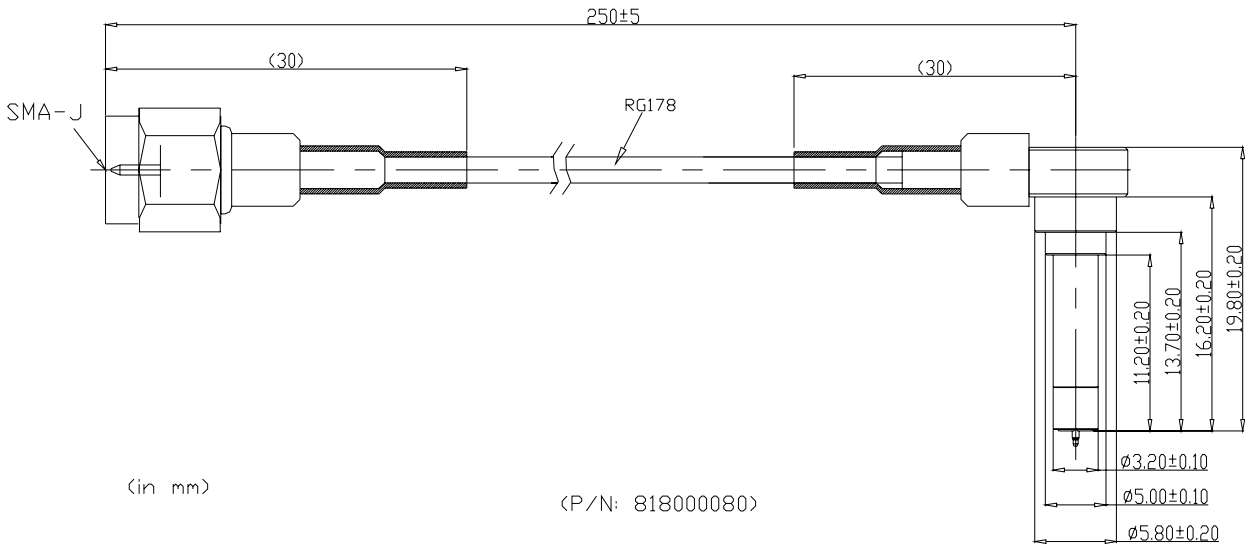
 Temperature:  $-10 \sim +40$  °C

Moisture: 15~85 % RH

Valid Period: 6 months

11、Accessories for Tests

TYPE I :



TYPY II :

